1 2	3 4	5 6 7 8
	·	RECOMMENDATION FOR SOLDER PROCESSING
har-flex straight male connected	or RoHS RoHS	Solder paste recommendation
compliant		The har-flex connectors are solderable with established lead-free SAC / SnNi solder but also leaded solder e.g. SnPb
ENERAL INFORMATIONS		PCB pad plating
		The har-flex connectors are solderable on lead-free pad surfaces like HAL, NiAu, Immersion Sn.
No. of contacts	from 6 to 100poles, all even numbers	Other all the common details
Contact spacing	1,27mm x 1,27mm [0,050"x0,050"]	Stencil recommendation  The colder deposition has to be placed on the pad area of the contact colder times
Test Voltage	500V	The solder deposition has to be placed on the pad area of the contact solder tines.  Ideally, the solder deposition has the same length-to-width ratio and center point like the PCB pads.
Contact resistance	< 25 mOhm	The size of the solder stencil apertures is depending on the thickness of the stencil.
Insulation resistance	≥ 10x10^9Ω	In general, the thinner stencils will need larger apertures to result in the required volume of solder paste.
Working current acc. to IEC 60512, at 70°C, 80% derating	see derating diagram	The minimum required solder paste volume for the signal pins is 0,094mm³, for the hold down it is 0,33mm³.  For example, this can be achieved with the following stencil data:
Working temperature range	-55°C +125°C	Signal pins
Termination technology	SMT	Stencil thickness PCB pad size proposal stencil aperture size calculated solder paste volume
Reflow processing temperature (acc. to ECA/IPC/JEDEC J-STD-075 Level PSL R0)	min. 150s > 217°C min. 30s > 240°C	120 μm 1,1 x 0,8 mm 1,05 x 0,75 mm 0,095 mm³
Clearance & creepage distance	0.4mm min.	150 µm 1,1 x 0,8 mm 0,99 x 0,72 mm 0,107 mm³
Insertion force (depending on mating connector)	approximately 0,5N/contact	Hold-downs
Withdrawal force (depending on mating connector)	approximately 0,5N/contact	Stencil thickness PCB pad size proposal stencil aperture size calculated solder paste volume
, , , , , , , , , , , , , , , , , , , ,	PL1 : 500 mating cycles	120 µm 2,5 x 1,2 mm 2,45 x 1,15 mm 0,338 mm³
Mating cycles	PL2 : 250 mating cycles	150 µm 2,5 x 1,2 mm 2,25 x 1,08 mm 0,365 mm <sup>3</sup>
RoHS - compliant	Yes	If a stencil with lower thickness shall be used, please insure the minimum required solder paste volume by enlarging t
Leadfree	Yes	stencil aperture. Depending on the PCB design, the solder deposition may protrude the PCB pads. But to achieve a g
Working voltage acc. to to IEC 60664-1	100V / 150V (depending on installation category)	sealing during solder paste printing and to reduce the cleaning interval of the stencil, the aperture should be smaller than the PCB pad about 10% or 25µm encircling.
UL file acc. UL 1977	ECBT2.E102079	Coplanarity of contacts
UL file acc. CSA-C22.2 (for Canada)	ECBT8.E102079	All connectors are tested for coplanarity of contacts and are in the range of 6 pin to 50 pin: ≤ 0,1mm
PSL level acc. ECA/IPC/JEDEC J-STD-075	PSL R0	52 pin to 68 pin: ≤ 0,12mm
MSL level acc. ECA/IPC/JEDEC J-STD-020D	MSL 1	70 pin to 80 pin: ≤ 0,12mm
NSULATOR MATERIAL		82 pin to 100 pin: <b>≤</b> 0,15mm
Matarial	LCD /liquid an etalling natures	Performance level
Material Color	LCP (liquid crystalline polymer)  Black	Performance level 1 (recommended for majority of applications) : 500 mating cycles with the following procedure
UL classification	UL94-V0	Initial 250 mating cycles, 10 days gas test (25°C / 75% r.h.) using H2S 10 ppb, NO2 200 ppb, CL2 10 ppb, SO2 200 pp
Material group acc. IEC 60664-1	IIIa (175≤CTI< 400)	Measurement of contact resistance. The remaining 250 mating cycles are subject to measurement of contact resistance
	IIIa (173 <b>5</b> C11 <b>~ 4</b> 00)	and visual inspection.  Visual inspection. No abrasion of the contact finish through to the base material. No functional impairment.
ONTACT MATERIAL		Part number definition: 15 2
Contact material	Copper alloy	
Plating termination zone	Sn	Performance level 2 : 250 mating cycles with the following procedure Initial 125 mating cycles, 4 days gas test (25°C / 75% r.h.) using H2S 10 ppb, NO2 200 ppb, CL2 10 ppb, SO2 200 ppb
Plating contact sliding side	Au over PdNi (acc. to Performance level)	Measurement of contact resistance. The remaining 125 mating cycles are subject to measurement of contact resistance
ERATING DIAGRAM acc. to IEC 60512-5 (Current carrying capac	city)	and visual inspection.
The transfer of the control of the c	,)	Visual inspection. No abrasion of the contact finish through to the base material. No functional impairment.  Part number definition: 15 6
The current carrying capacity is limited by maximum temperature of materials for inserts and contacts including terminals.  The current capacity curve is valid for continuous, non	[A] be [A]	Performance level S4 : 500 mating cycles Defined contact surface of min. 0,06 µm Au over 0,7+0,2µm PdNi Part number definition : 15 5
interrupted current loaded contacts of connectors when simultaneous power on all contacts is given, without exceeding the maximum temperature.	1	All Dimensions in mm Original Size DIN A3 1:1   Free size tol.   Ref.   Sub.    All rights reserved   Created by ZHUANGJ   Inspected by LUOK   Standardisation ROEBEN   Date 2021-12-16   Final Release
Control and test procedures according to DIN IEC 60512-	0 10 20 30 40 50 60 70 80 90 100 110 120 130	Department EL PD  Title har-flex male THR stacking height 1.75, 3.25 and 4.85  Doc-Key / EC 100670462/JOB
derating curve at Imax*0,8 (IEC 60512-5-2)	Tomporeting [9C]	INARTINU
derating curve at Imax*0,8 (IEC 60512-5-2)	Temperature [°C]	D-32339 Espelkamp  Type DS  Number 15111100200  Rev. B

